



## STP04CM596

### 4-Bit constant current for power-LED LED sink driver

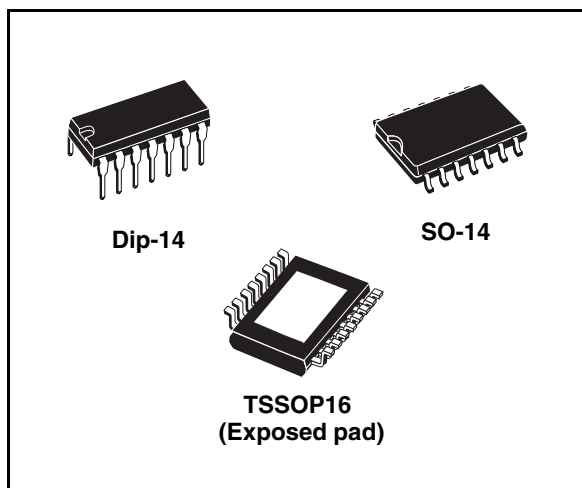
#### General features

- 4 constant current output channels
- Adjustable output current through one external resistor
- Serial data IN/parallel data OUT
- Serial OUT change state on the falling edges of clock
- Four outputs current: 80-500mA
- 25MHz clock frequency
- Available in high thermal TSSOP exposed pad.

#### Description

The STP04CM596 is a high-power LED Driver and 4-bit shift register designed for PowerLED applications.

The STP04CM596 contains a 4-bit serial IN, parallel OUT shift register that feeds a 4-bit D-type storage register. In the output stage, four regulated current sources were designed to provide 80-500mA constant current to drive the high powered LEDs.



The STP04CM596 guarantees 16V output driving capability, allowing users to connect more LEDs in series. The high clock frequency, 25 MHz, also satisfies the system requirements which include high volume data transmission.

The STP04CM596 is well suited for very high brightness displays and special lighting applications.

The STP04CM596 is offered in DIP-14, SO-14 and TSSOP16 Exposed Pad packages.

#### Order codes

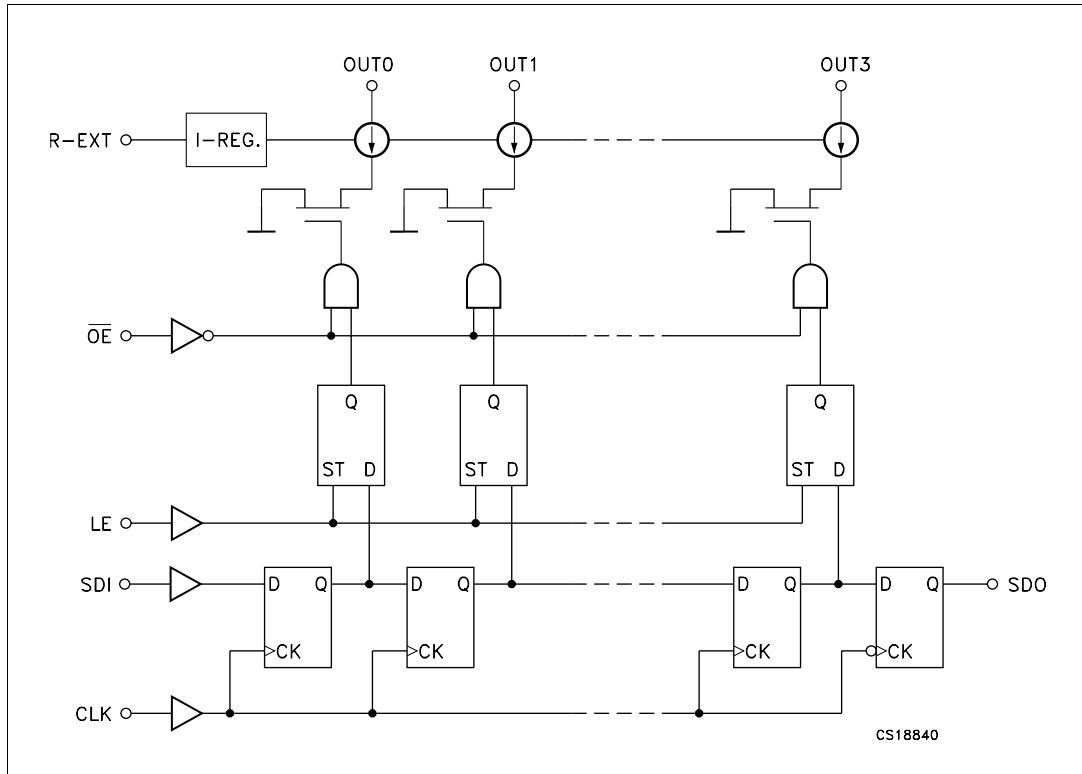
Part Number	Package	Packaging
STP04CM596B1R	DIP-14	25 parts per tube
STP04CM596M	SO-14 (Tube)	50 parts per tube
STP04CM596MTR	SO-14 (Tape & Reel)	2500 parts per reel
STP04CM596XTTR	TSSOP16 Exposed-pad (Tape & Reel)	2500 parts per reel

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# 1 Internal schematic

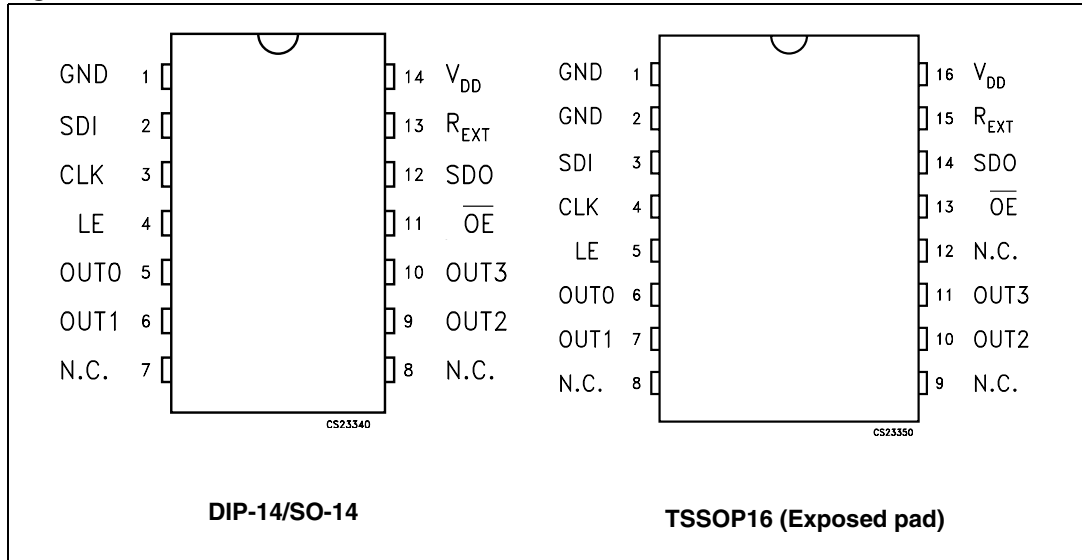
Figure 1. Block diagram



## 2 Pin settings

### 2.1 Pin connection

Figure 2. Pin connection



### 2.2 Pin description

Table 1. Pin description

DIP-14 and SO-14 Pin N°	TSSOP16 Pin N°	Symbol	Name and function
1	1, 2	GND	Ground terminal
2	3	SDI	Serial data input terminal
3	4	CLK	Clock input terminal
4	5	LE	Latch input terminal
5	6	OUT 0	Output terminal
6	7	OUT 1	Output terminal
7, 8	8, 9, 12	N.C.	Not connected
9	10	OUT 2	Output terminal
10	11	OUT 3	Output terminal
11	13	$\overline{OE}$	Output enable input terminal (active low)
12	14	SDO	Serial data out terminal
13	15	R-EXT	Constant current programming
14	16	$V_{DD}$	5V supply voltage terminal

### 3 Maximum rating

Stressing the device above the rating listed in the “Absolute Maximum Ratings” table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
V <sub>DD</sub>	Supply voltage	0 to 7	V
V <sub>O</sub>	Output voltage	-0.5 to 16	V
I <sub>O</sub>	Output current	500	mA
V <sub>I</sub>	Input voltage	-0.4 to V <sub>DD</sub> +0.4	V
I <sub>GND</sub>	GND terminal current	2000	mA
f <sub>CLK</sub>	Clock frequency	25	MHz
T <sub>OPR</sub>	Operating temperature range	-40 to +125	°C
T <sub>STG</sub>	Storage temperature range	-55 to +150	°C

#### 3.1 Thermal data

**Table 3. Thermal data**

Symbol	Parameter	DIP-14	SO-14	TSSOP16	Unit
R <sub>thJA</sub>	Thermal resistance junction-ambient	70 <sup>(1)</sup>	105 <sup>(2)</sup>	37.5 <sup>(3)</sup>	°C/W

- 1W of dissipated power, mounted on the board
- 1W of dissipated power, mounted on SM PCB1 SGS board
- Using the PCB Multi-Layer JEDEC Standard Test Boards

## 3.2 Recommended operating conditions

Table 4. Recommended operating conditions

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{DD}$	Supply voltage		3.3	5.0	5.5	V
$V_O$	Output voltage				16.0	V
$I_O$	Output current	OUTn $V_{DD} = 5V$	80		500	mA
$I_{OH}$	Output current	Serial-OUT			+1	mA
$I_{OL}$	Output current	Serial-OUT			-1	mA
$V_{IH}$	Input voltage		$0.7V_{DD}$		$V_{DD}+0.3$	V
$V_{IL}$	Input voltage		-0.3		$0.3V_{DD}$	V
$t_{wLAT}$	LE pulse width	$V_{DD} = 3.0$ to $3.6V$	20	6.5		ns
$t_{wCLK}$	CLK pulse width		20	7.0		ns
$t_{wEN}$	$\overline{OE}$ pulse width		400	100		ns
$t_{SETUP(D)}$	Setup time for DATA		20	3.3		ns
$t_{HOLD(D)}$	Hold time for DATA		15	1.5		ns
$t_{SETUP(L)}$	Setup time for LATCH		15	5		ns
$t_{HOLD(E)}$	Hold time for ENABLE		60	38		ns
$f_{CLK}$	Clock frequency	Cascade operation <sup>(1)</sup>			25	MHz
$T_{OPR}$	Operating temperature range		-40		+125	°C

1. If multiple devices are cascaded, it may not be possible to achieve the maximum data transfer. Please consider the timing conditions carefully.

## 4 Electrical characteristics

**Table 5. Current accuracy**

Output voltage	Current accuracy		Output current
	Between bits	Between ICs	
$\geq 0.7V$	Typ. $\pm 1\%$	$\pm 6\%$	80 to 500 mA

**Table 6. Electrical characteristics** ( $V_{DD} = 5V$ ,  $T_A = 25^\circ C$ , unless otherwise specified.)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{IH}$	Input voltage high level		$0.7V_{DD}$		$V_{DD}$	V
$V_{IL}$	Input voltage low level		GND		$0.3V_{DD}$	V
$I_{OH}$	Output leakage current	$V_{OH} = 16V$			10	$\mu A$
$V_{OL}$	Output voltage (Serial-OUT)	$I_{OL} = 1mA$			0.4	V
$V_{OH}$	Output voltage (Serial-OUT)	$I_{OH} = -1mA$	$V_{DD}-0.4V$			V
$I_{OL1}$	Output current	$V_O = 0.7V R_{EXT} = 910\ \Omega$	77	82	87	mA
$I_{OL2}$		$V_O = 0.7V R_{EXT} = 160\ \Omega$	470	500	530	mA
$\Delta I_{OL1}$	Output current error between bit (All Output ON)	$V_O = 0.7V R_{EXT} = 910\ \Omega$		1	$\pm 3$	%
$\Delta I_{OL2}$		$V_O = 0.7V R_{EXT} = 160\ \Omega$		0.5	$\pm 3$	%
$R_{SIN(up)}$	Pull-up resistor		150	300	600	$K\Omega$
$R_{SIN(down)}$	Pull-down resistor		100	200	400	$K\Omega$
$I_{DD(OFF1)}$	Supply current (OFF)	$R_{EXT} = OPEN$ OUT 0 to 3 = OFF		0.3	0.6	mA
$I_{DD(OFF2)}$		$R_{EXT} = 470\ \Omega$ OUT 0 to 3 = OFF		5.2	8.0	
$I_{DD(OFF3)}$		$R_{EXT} = 250\ \Omega$ OUT 0 to 3 = OFF		8.0	12	
$I_{DD(ON1)}$	Supply current (ON)	$R_{EXT} = 470\ \Omega$ OUT 0 to 3 = ON		5.6	8.0	
$I_{DD(ON2)}$		$R_{EXT} = 250\ \Omega$ OUT 0 to 3 = ON		8.3	12	

**Table 7. Switching characteristics** ( $V_{DD}=5V$ ,  $T = 25^{\circ}C$ , unless otherwise specified.)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$t_{PLH1}$	Propagation delay time, $\overline{CLK}-\overline{OUTn}$ , $LE = H$ , $\overline{OE} = L$	$V_{DD} = 5V$ $V_{IH} = V_{DD}$ $V_{IL} = GND$ $C_L = 13pF$ $I_O = 40mA$ $V_L = 3V$ $R_{EXT} = 470\ \Omega$ $R_L = 65\ \Omega$		100	160	ns
$t_{PLH2}$	Propagation delay time, $\overline{LE}-\overline{OUTn}$ , $\overline{OE} = L$			100	150	ns
$t_{PLH3}$	Propagation delay time, $\overline{OE}-\overline{OUTn}$ , $LE = H$			90	140	ns
$t_{PLH}$	Propagation delay time, $\overline{CLK}-\overline{SDO}$			30	40	ns
$t_{PHL1}$	Propagation delay time, $\overline{CLK}-\overline{OUTn}$ , $LE = H$ , $\overline{OE} = L$			40	60	ns
$t_{PHL2}$	Propagation delay time, $\overline{LE}-\overline{OUTn}$ , $\overline{OE} = L$			35	50	ns
$t_{PHL3}$	Propagation delay time, $\overline{OE}-\overline{OUTn}$ , $LE = H$			40	70	ns
$t_{PHL}$	Propagation delay time, $\overline{CLK}-\overline{SDO}$			30	40	ns
$t_r$	Output rise time <sup>(1)</sup>	$V_O = 1.6V$ , $R_L = 1\ \Omega$		300	400	ns
$t_f$	Output fall time <sup>(1)</sup>	$R_{EXT} = 470\ \Omega$		55	80	ns

1. If multiple devices are cascaded, it may not be possible to achieve the maximum data transfer. Please consider the timing conditions carefully.



## 5 Equivalent circuit of inputs and outputs

Figure 3.  $\overline{OE}$  terminal

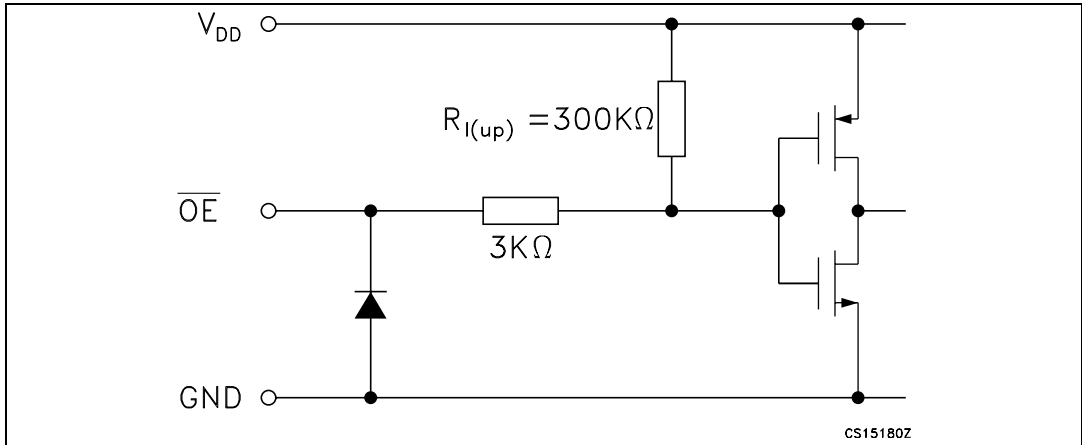


Figure 4. LE terminal

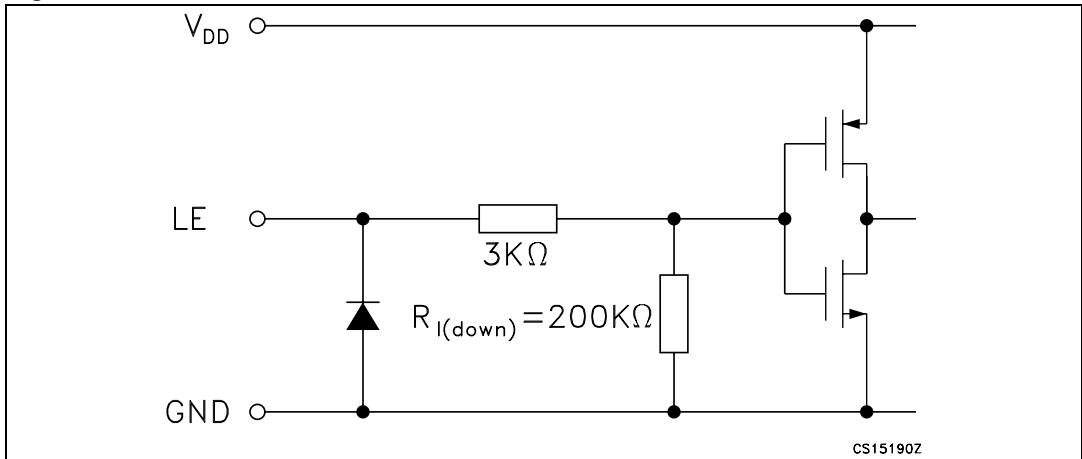


Figure 5. CLK, SDI terminal

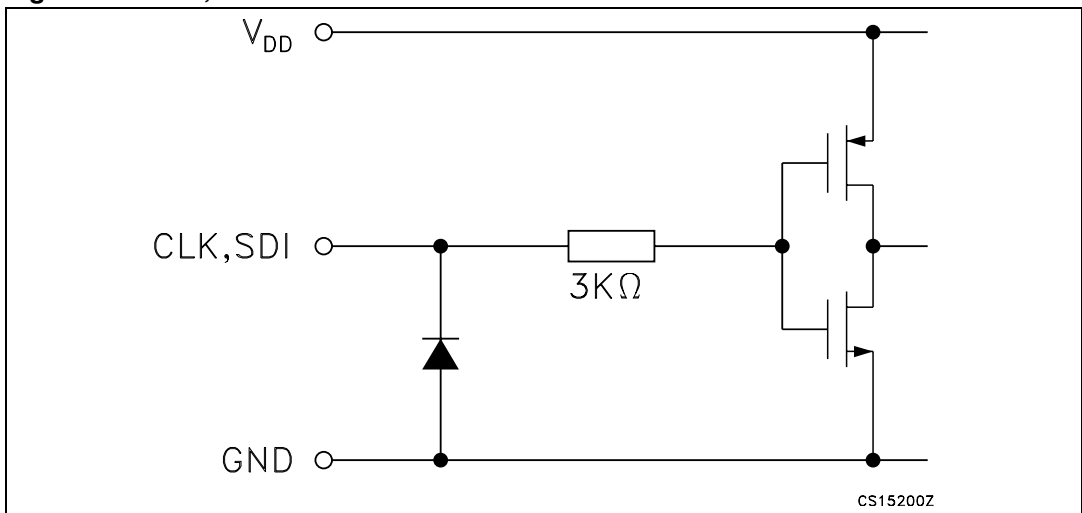
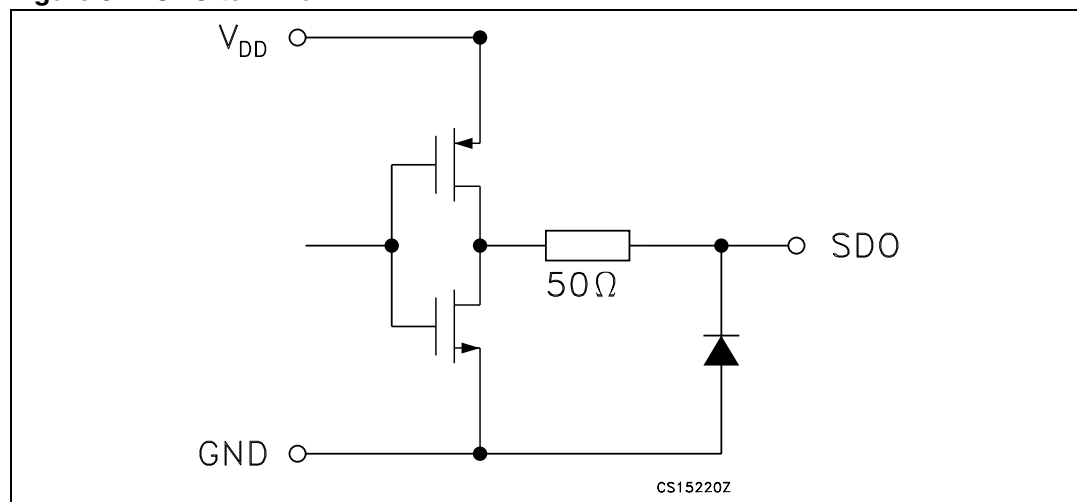
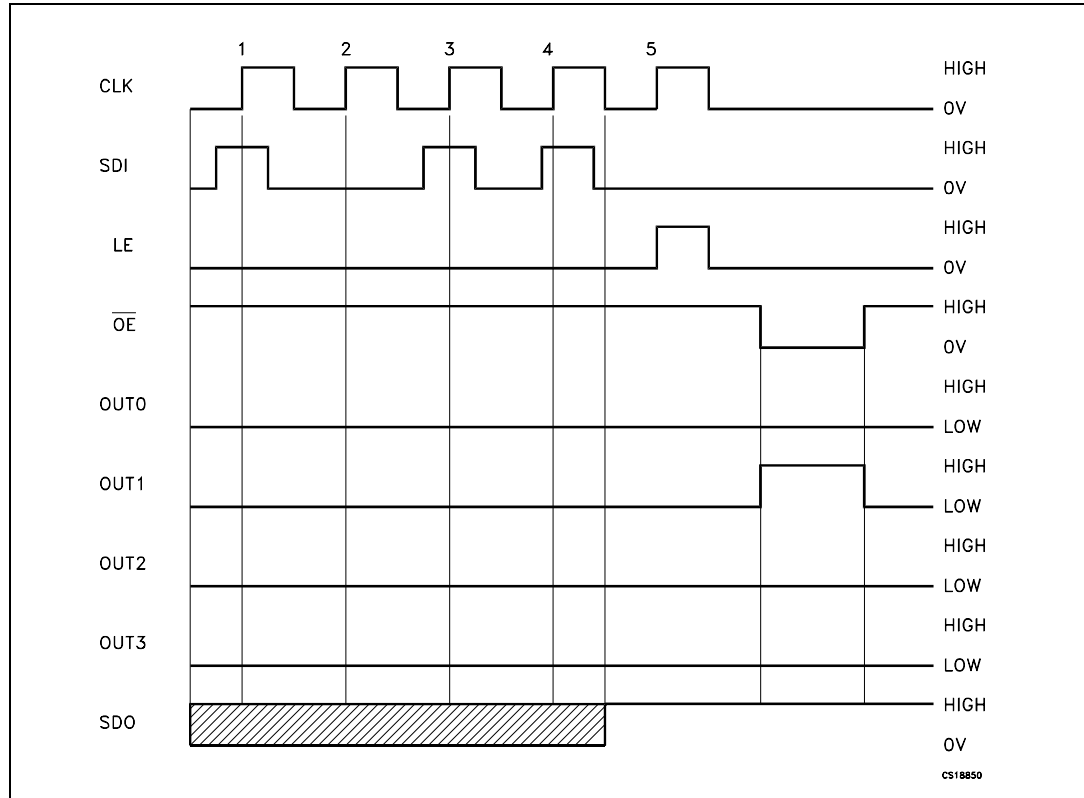


Figure 6. SDO terminal



## 6 Timing diagrams

Figure 7. Timing diagram



Note: The latches circuit holds data when the LE terminal is Low.

- 1 When the LE terminal is at a High level, the latch circuit holds the data it passes from the input to the output.
- 2 When the  $\overline{OE}$  terminal is at a Low level, the output terminals OUT0 to OUT3 respond to the data, either ON or OFF.
- 3 When the  $\overline{OE}$  terminal is at a High level, it switches off all the data on the output terminal.

Figure 8. Clock, serial-IN, serial-OUT

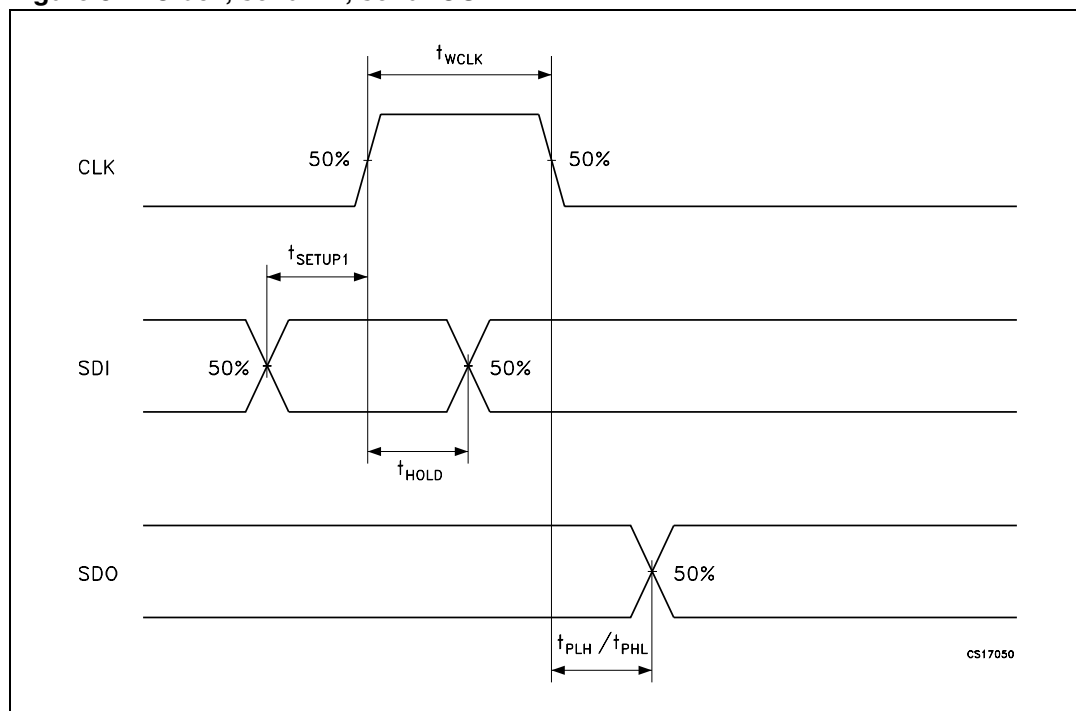


Figure 9. Clock, serial-IN, latch, enable, outputs

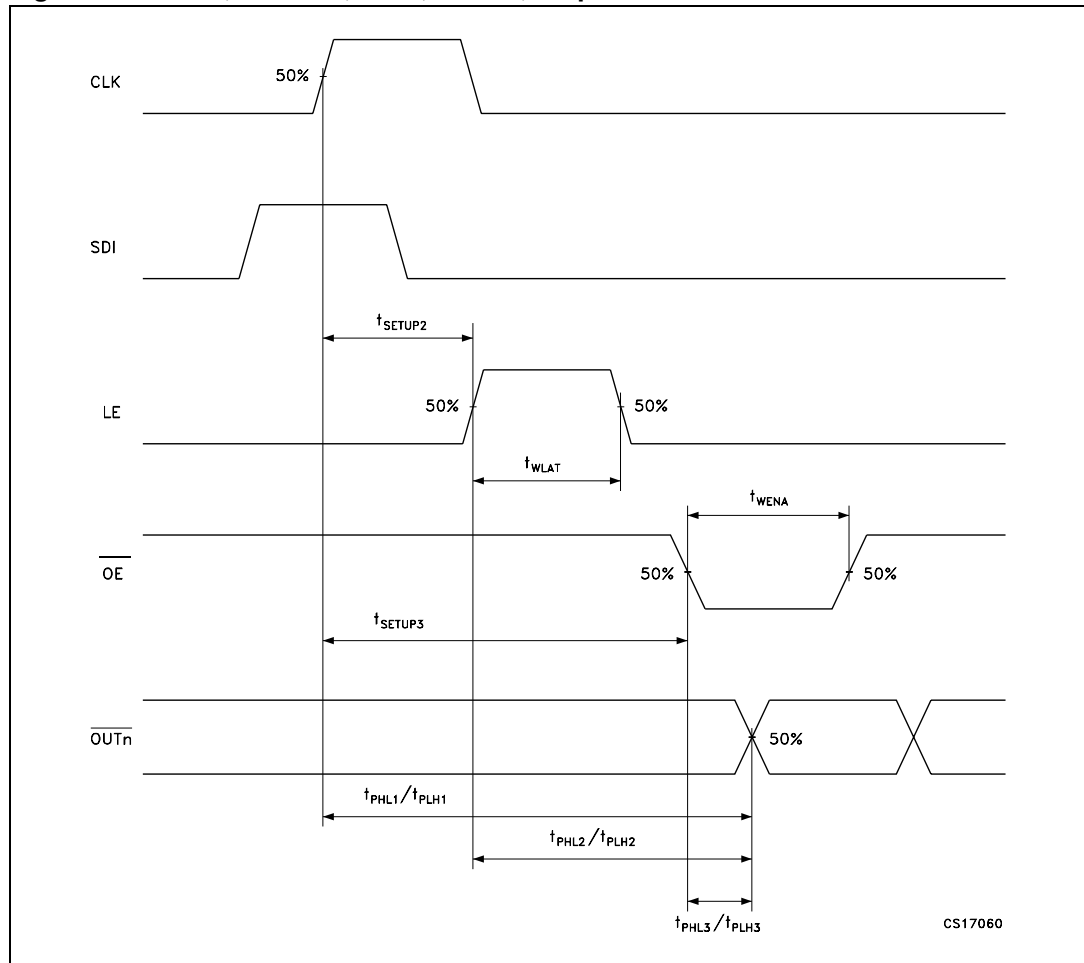
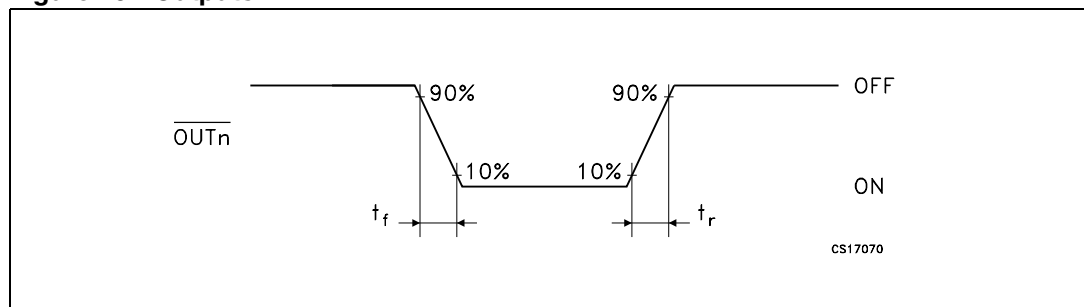


Figure 10. Outputs



# 7 Test circuit

Figure 11. DC characteristic

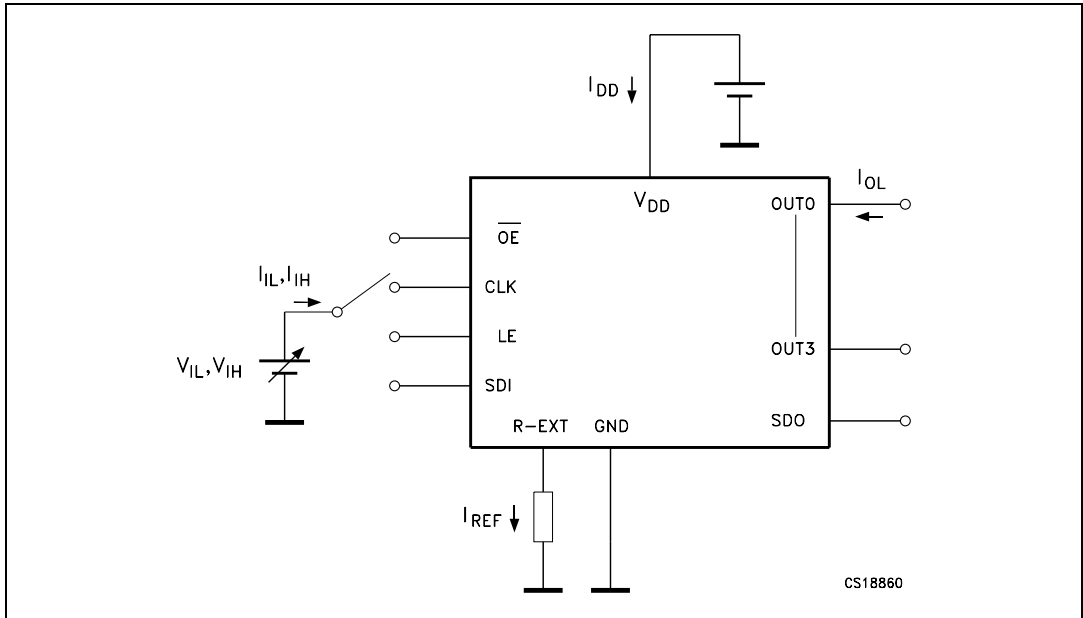
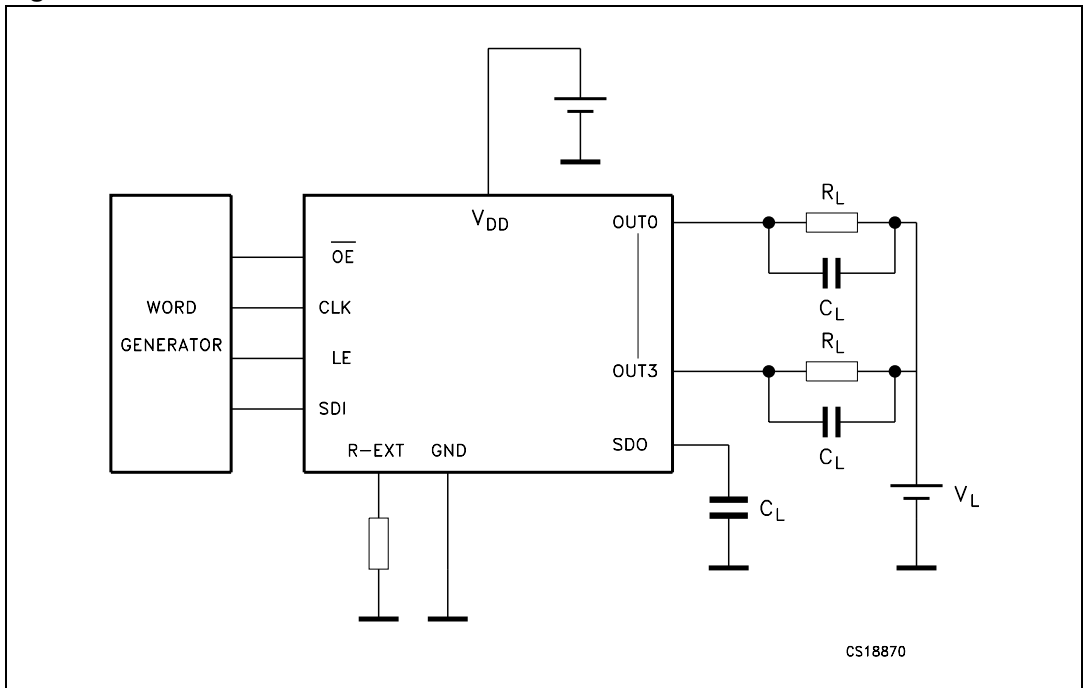


Figure 12. AC characteristic



# 8 Typical characteristics

Figure 13. Output current- $R_{EXT}$  resistor

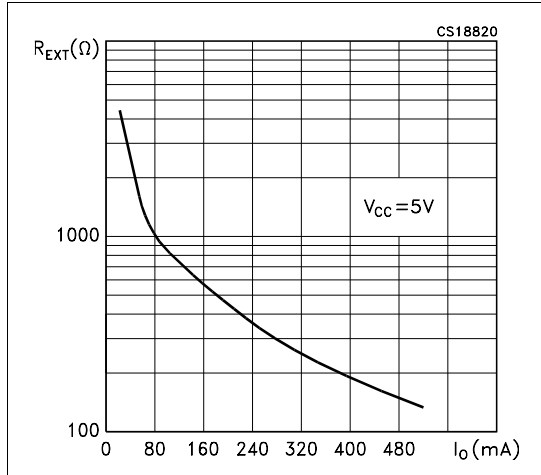


Figure 14. Output current vs dropout voltage

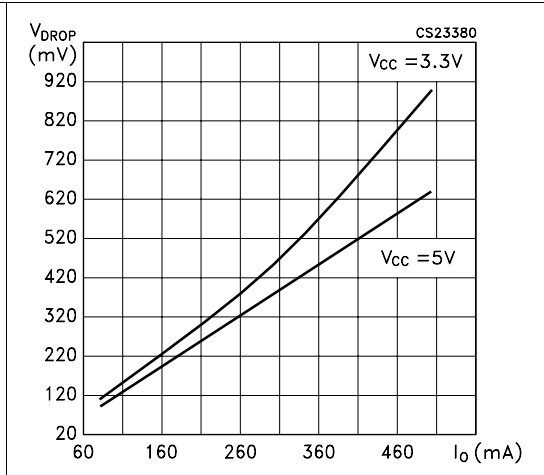


Figure 15. Output current vs  $\pm\Delta I_{OL}$  (%)

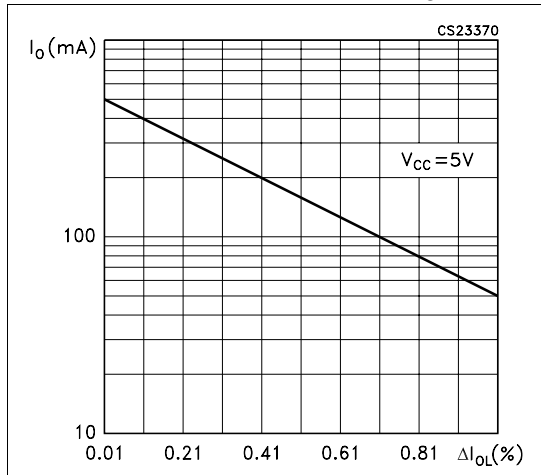
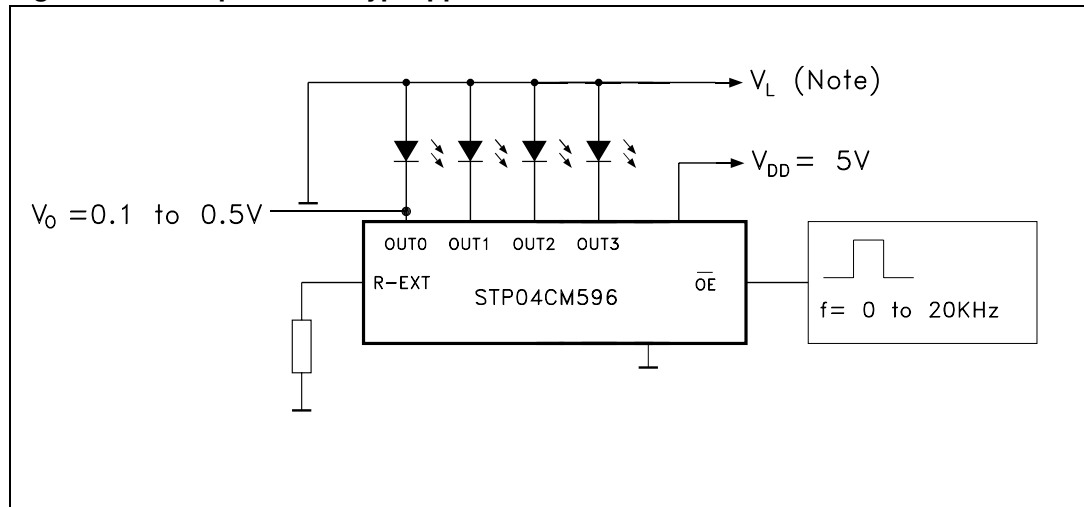
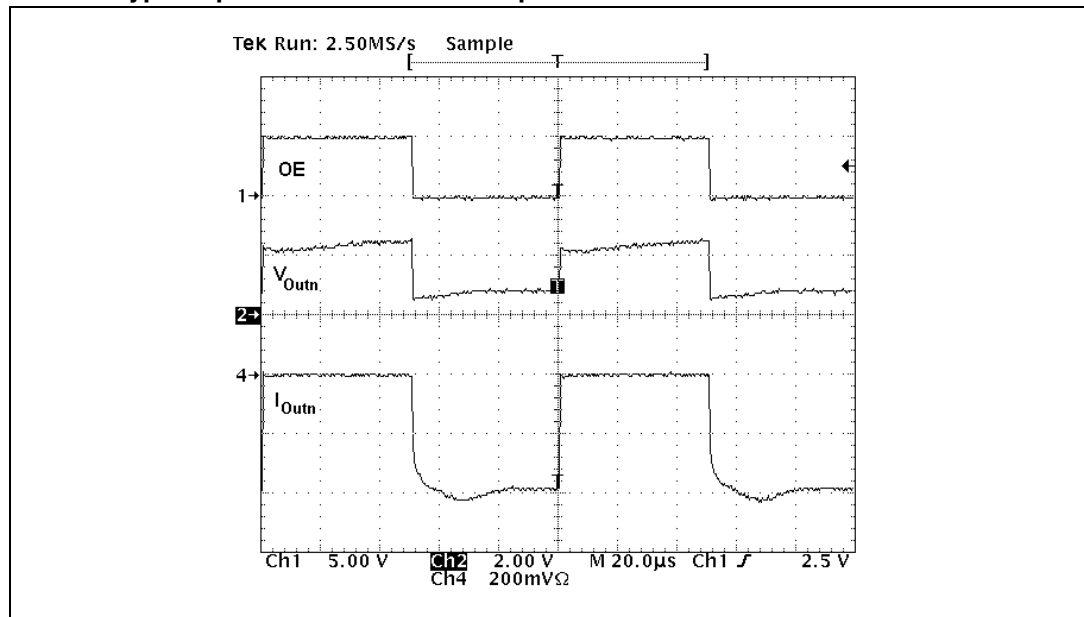


Figure 16. Blue powerLED typ. application circuit



Note:  $V_L$  will be determined by the  $V_F$  of the LEDs

Table 8. Typ. output waveform with blue powerLEDs





## 9 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

Table 9. DIP-14 mechanical data

Dim.	mm.			inch		
	Min	Typ	Max	Min	Typ	Max
a1	0.51			0.020		
B	1.39		1.65	0.055		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		15.24			0.600	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z	1.27		2.54	0.050		0.100

Figure 17. Package dimensions

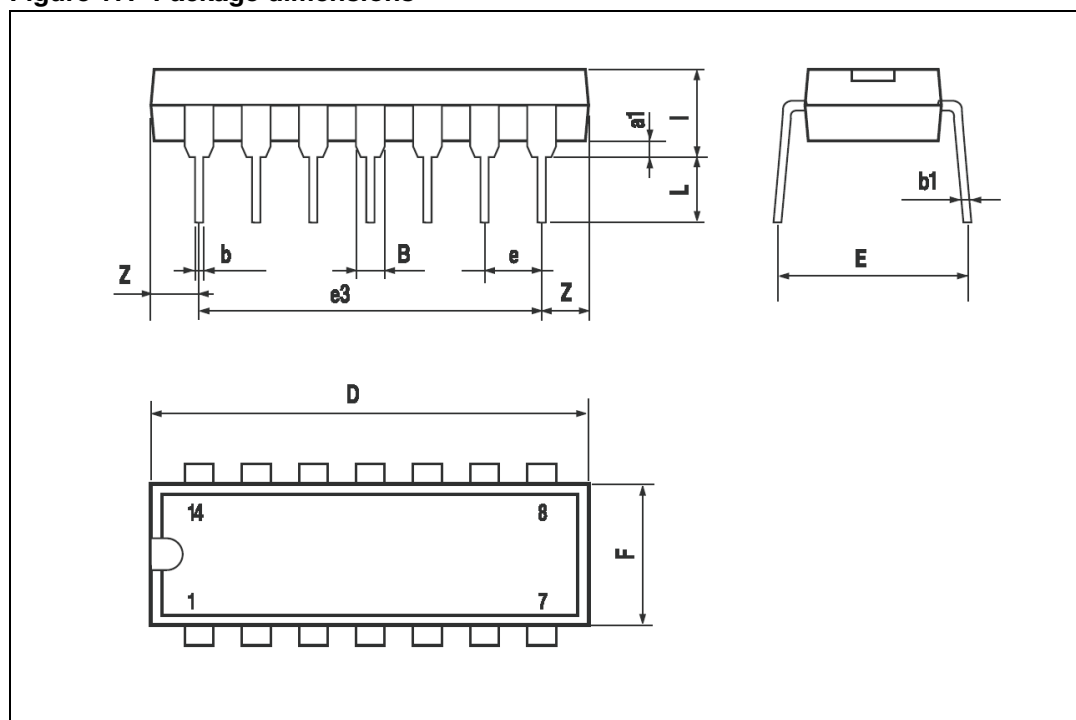


Table 10. SO-14 mechanical data

Dim.	mm.			inch		
	Min	Typ	Max	Min	Typ	Max
A			1.75			0.068
a1	0.1		0.2	0.003		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	8.55		8.75	0.336		0.344
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		7.62			0.300	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.68			0.026
S	8° (max.)					

Figure 18. Package dimensions

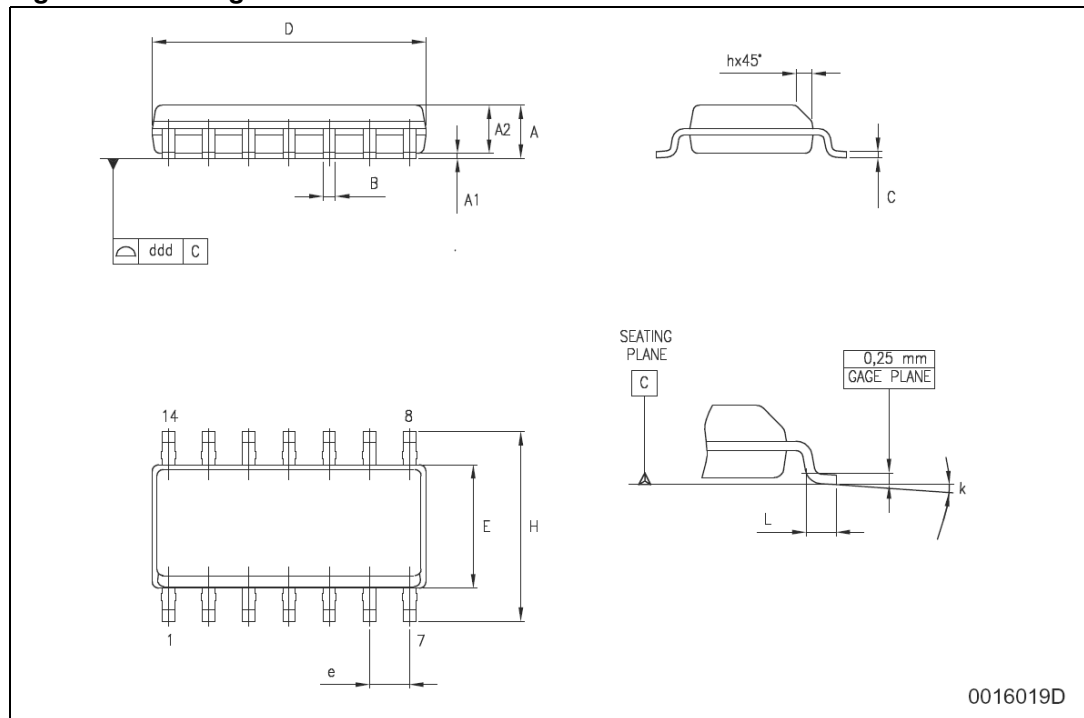


Table 11. TSSOP16 (Exposed pad) mechanical data

Dim.	mm.			inch		
	Min	Typ	Max	Min	Typ	Max
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0079
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030

Figure 19. Package dimensions

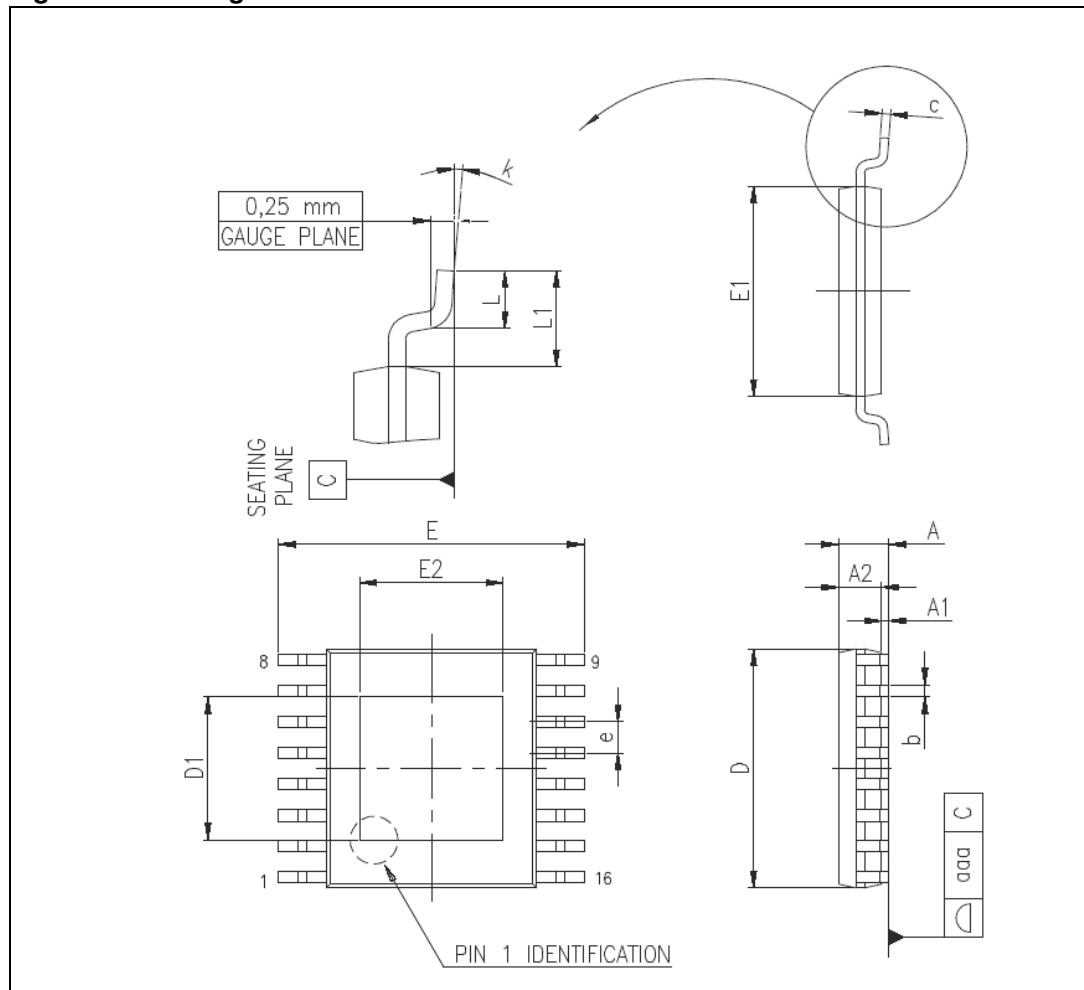


Table 12. Tape and reel SO-14

Dim.	mm.			inch		
	Min	Typ	Max	Min	Typ	Max
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.4		6.6	0.252		0.260
Bo	9		9.2	0.354		0.362
Ko	2.1		2.3	0.082		0.090
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319

Figure 20. Tape and reel dimensions

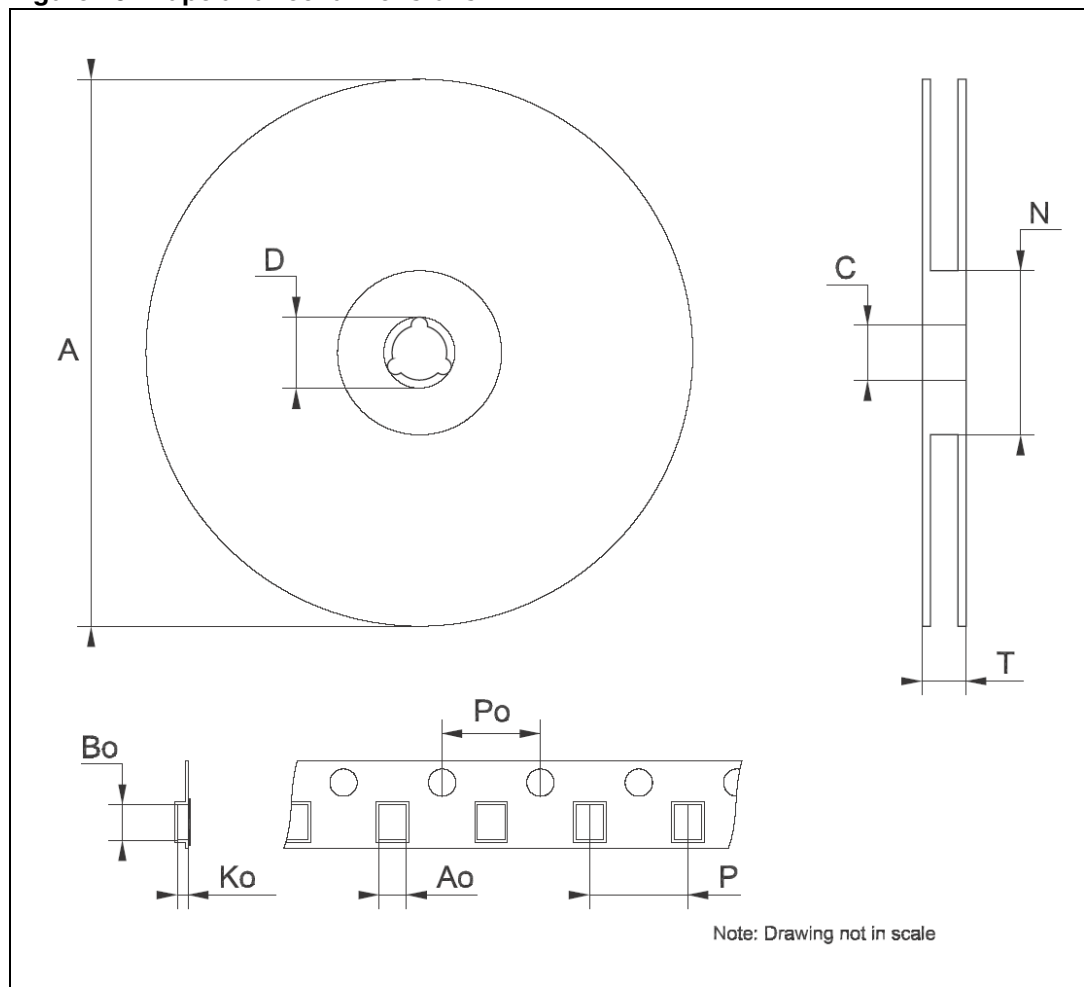
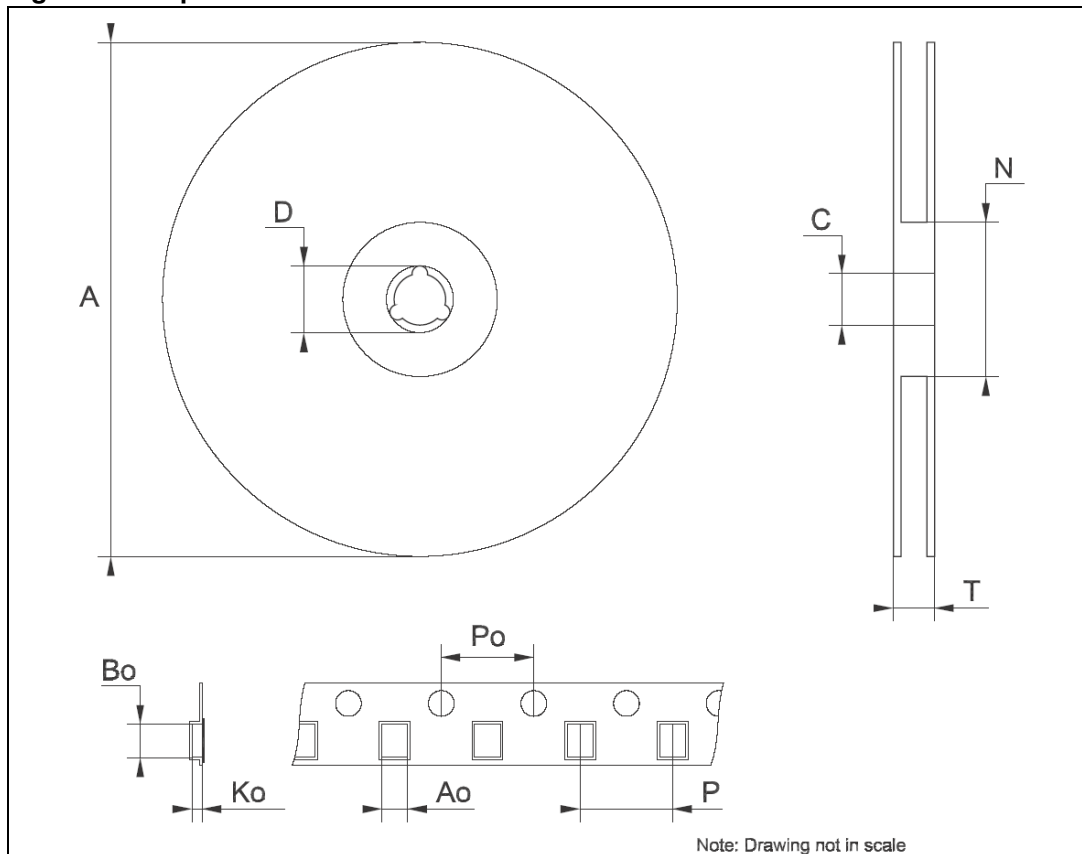


Table 13. TSSOP16 tape and reel

Dim.	mm.			inch		
	Min	Typ	Max	Min	Typ	Max
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.7		6.9	0.264		0.272
Bo	5.3		5.5	0.209		0.217
Ko	1.6		1.8	0.063		0.071
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319

Figure 21. Tape and reel dimensions



## 10 Revision history

**Table 14. Revision history**

Date	Revision	Changes
26-Oct-2006	1	Initial release
05-Apr-2006	2	New template
23-May-2006	3	Updated packaging information
08-Jun-2006	4	Typos in cover page
20-Jun-2006	5	Block diagram updated <i>Figure 1 on page 3</i> , equivalent circuits updated <i>Figure 3, 4, 5, 6, on page 9 and 10</i>

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